

PSMN008-75P; PSMN008-75B

N-channel enhancement mode field-effect transistor

Rev. 01 — 18 September 2000

Product specification

1. Description

N-channel enhancement mode field-effect transistor in a plastic package using TrenchMOS™¹ technology.

Product availability:

PSMN008-75P in SOT78

PSMN008-75B in SOT404 (D²-PAK).

2. Features

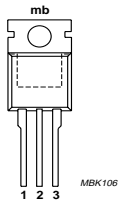
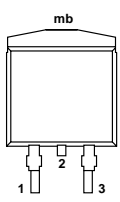
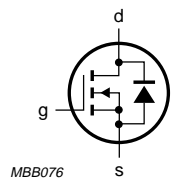
- Fast switching
- Low on-state resistance
- Avalanche ruggedness rated.

3. Applications

- DC to DC converters
- Uninterruptable power supplies.

4. Pinning information

Table 1: Pinning - SOT78 and SOT404, simplified outline and symbol

Pin	Description	Simplified outline	Symbol
1	gate (g)	 SOT78	 SOT404 (D ² -PAK)
2	drain (d) [1]		
3	source (s)		
mb	connected to drain (d)		
		 MBB076	

[1] It is not possible to make connection to pin 2 of the SOT404 package.

1. TrenchMOS is a trademark of Royal Philips Electronics.



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5. Quick reference data

Table 2: Quick reference data

Symbol	Parameter	Conditions	Typ	Max	Unit
V_{DS}	drain-source voltage (DC)	$T_j = 25$ to 175 °C	–	75	V
I_D	drain current (DC)	$T_{mb} = 25$ °C; $V_{GS} = 10$ V	–	75	A
P_{tot}	total power dissipation	$T_{mb} = 25$ °C	–	230	W
T_j	junction temperature		–	175	°C
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10$ V; $I_D = 25$ A	7.9	8.5	mΩ

6. Limiting values

Table 3: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

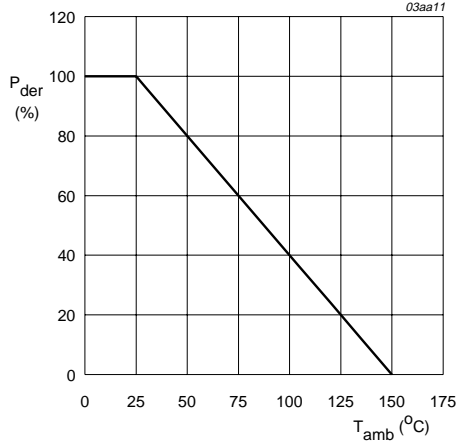
Symbol	Parameter	Conditions	Min	Max	Unit
V_{DS}	drain-source voltage (DC)	$T_j = 25$ to 175 °C	–	75	V
V_{DGR}	drain-gate voltage (DC)	$T_j = 25$ to 175 °C; $R_{GS} = 20$ kΩ	–	75	V
V_{GS}	gate-source voltage (DC)		–	±20	V
I_D	drain current (DC)	$T_{mb} = 25$ °C; $V_{GS} = 10$ V; Figure 2 and 3	–	75	A
		$T_{mb} = 100$ °C; $V_{GS} = 10$ V; Figure 2 and 3	–	75	A
I_{DM}	peak drain current	$T_{mb} = 25$ °C; pulsed; $t_p \leq 10$ μs; Figure 2 and 3	–	240	A
P_{tot}	total power dissipation	$T_{mb} = 25$ °C; Figure 1	–	230	W
T_{stg}	storage temperature		–55	+175	°C
T_j	operating junction temperature		–55	+75	°C

Source-drain diode

I_S	source (diode forward) current (DC)	$T_{mb} = 25$ °C	–	75	A
I_{SM}	peak source (diode forward) current	$T_{mb} = 25$ °C; pulsed; $t_p \leq 10$ μs	–	240	A

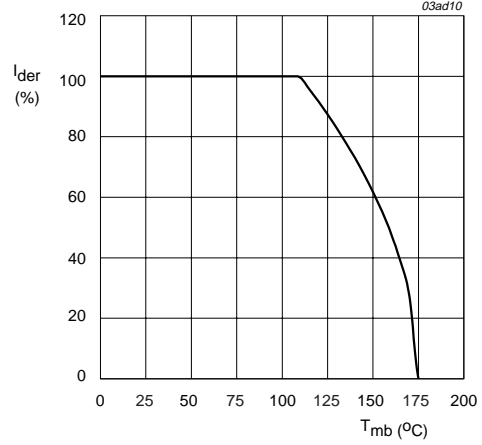
Avalanche ruggedness

E_{AS}	non-repetitive avalanche energy	unclamped inductive load; $I_D = 75$ A; $t_p = 0.1$ ms; $V_{DD} \leq 15$ V; $R_{GS} = 50$ Ω; $V_{GS} = 10$ V; starting $T_j = 25$ °C; Figure 4	–	360	mJ
I_{AS}	non-repetitive avalanche current	unclamped inductive load; $V_{DD} \leq 15$ V; $R_{GS} = 50$ Ω; $V_{GS} = 10$ V; Figure 4	–	75	A



$$P_{der} = \frac{P_{tot}}{P_{tot(25^{\circ}C)}} \times 100\%$$

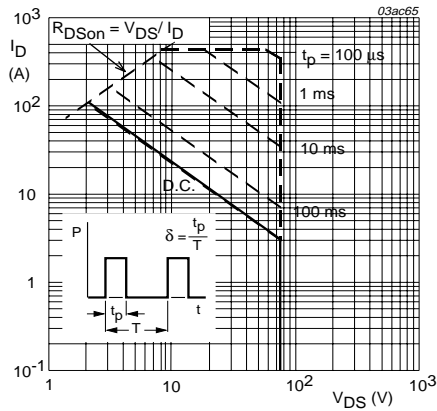
Fig 1. Normalized total power dissipation as a function of mounting base temperature.



$$V_{GS} \geq 10 \text{ V}$$

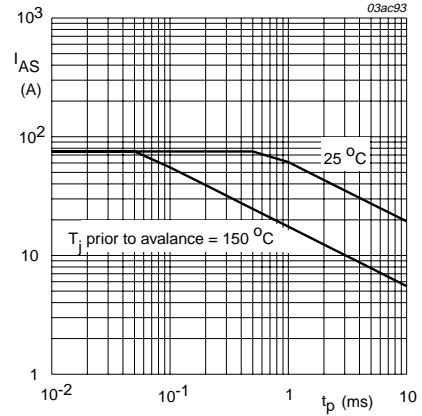
$$I_{der} = \frac{I_D}{I_{D(25^{\circ}C)}} \times 100\%$$

Fig 2. Normalized continuous drain current as a function of mounting base temperature.



$T_{mb} = 25^{\circ}C$; I_{DM} is single pulse

Fig 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage.



Unclamped inductive load; $V_{DD} \leq 15 \text{ V}$; $R_{GS} = 50 \Omega$; $V_{GS} = 10 \text{ V}$; starting $T_j = 25^{\circ}C$ and $150^{\circ}C$.

Fig 4. Non-repetitive avalanche ruggedness current as a function of pulse duration.

7. Thermal characteristics

Table 4: Thermal characteristics

Symbol	Parameter	Conditions	Value	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Figure 5	0.65	K/W
$R_{th(j-amb)}$	thermal resistance from junction to ambient	SOT78 package; vertical in still air	60	K/W
		SOT404 package; mounted on printed circuit board; minimum footprint.	50	K/W

7.1 Transient thermal impedance

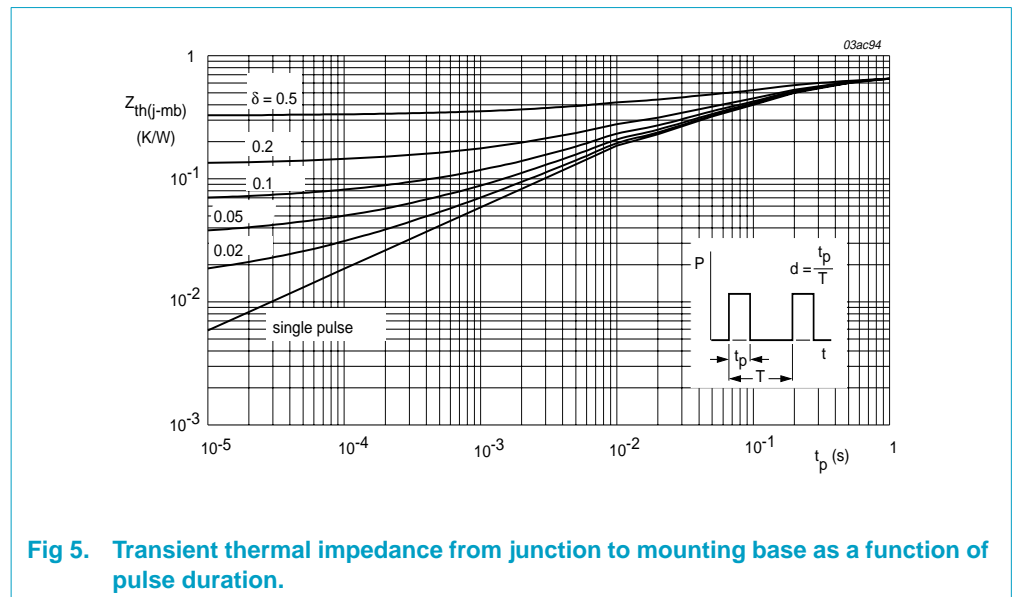


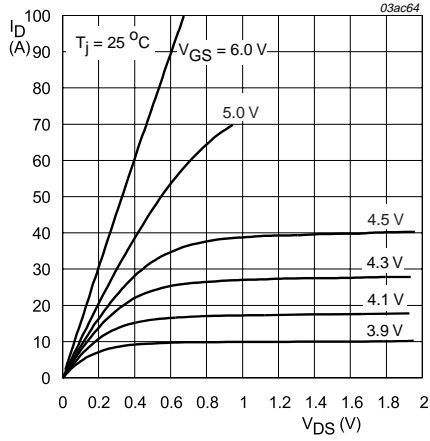
Fig 5. Transient thermal impedance from junction to mounting base as a function of pulse duration.

8. Characteristics

Table 5: Characteristics

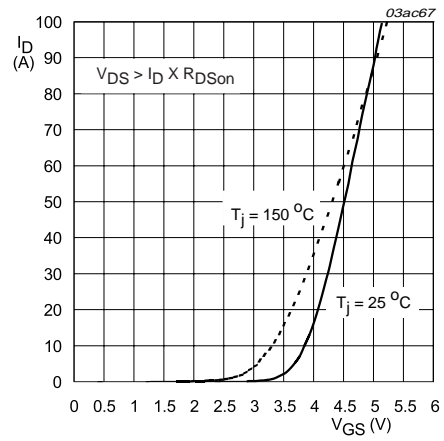
$T_j = 25\text{ °C}$ unless otherwise specified

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Static characteristics						
$V_{(BR)DSS}$	drain-source breakdown voltage	$I_D = 250\ \mu\text{A}$; $V_{GS} = 0\ \text{V}$	75	90	–	V
$V_{GS(th)}$	gate-source threshold voltage	$I_D = 1\ \text{mA}$; $V_{DS} = V_{GS}$; Figure 10				
		$T_j = 25\text{ °C}$	2	3	4	V
		$T_j = 175\text{ °C}$	1	–	–	V
I_{DSS}	drain-source leakage current	$V_{GS} = 0\ \text{V}$; $V_{DS} = 75\ \text{V}$				
		$T_j = 25\text{ °C}$	–	0.05	10	μA
		$T_j = 175\text{ °C}$	–	–	500	μA
I_{GSS}	gate-source leakage current	$V_{DS} = 0\ \text{V}$; $V_{GS} = \pm 20\ \text{V}$	–	4	100	nA
$R_{DS(on)}$	drain-source on-state resistance	$V_{GS} = 10\ \text{V}$; $I_D = 25\ \text{A}$; Figure 8 and 9				
		$T_j = 25\text{ °C}$	–	7.9	8.5	m Ω
		$T_j = 175\text{ °C}$	–	–	20	m Ω
Dynamic characteristics						
$Q_{g(tot)}$	total gate charge	$I_D = 75\ \text{A}$; $V_{DS} = 60\ \text{V}$; $V_{GS} = 10\ \text{V}$; Figure 15	–	115	–	nC
Q_{gs}	gate-source charge		–	21	–	nC
Q_{gd}	gate-drain (Miller) charge		–	50	–	nC
C_{iss}	input capacitance	$V_{GS} = 0\ \text{V}$; $V_{DS} = 25\ \text{V}$; $f = 1\ \text{MHz}$; Figure 13	–	4.7	–	nF
C_{oss}	output capacitance		–	760	–	pF
C_{rss}	reverse transfer capacitance		–	400	–	pF
$t_{d(on)}$	turn-on delay time	$V_{DD} = 37.5\ \text{V}$; $R_D = 1.5\ \Omega$; $V_{GS} = 10\ \text{V}$; $R_G = 10\ \Omega$	–	18	–	ns
t_r	turn-off rise time		–	80	–	ns
$t_{d(off)}$	turn-off delay time		–	170	–	ns
t_f	turn-off fall time		–	100	–	ns
Source-drain diode						
V_{SD}	source-drain (diode forward) voltage	$I_S = 25\ \text{A}$; $V_{GS} = 0\ \text{V}$; Figure 14	–	0.8	1.2	V
t_{rr}	reverse recovery time	$I_S = 5\ \text{A}$; $dI_S/dt = -100\ \text{A}/\mu\text{s}$;	–	80	–	ns
Q_r	recovered charge	$V_{GS} = 0\ \text{V}$; $V_R = 30\ \text{V}$	–	227	–	nC



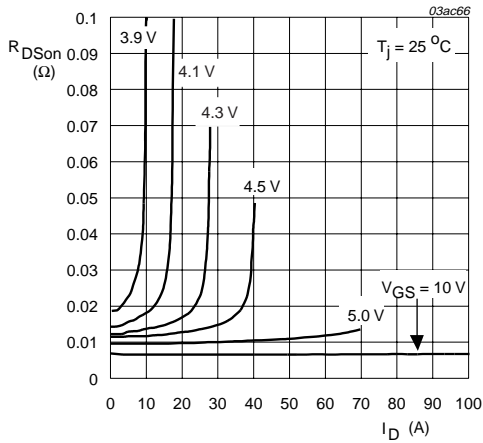
$T_j = 25\text{ }^\circ\text{C}$

Fig 6. Output characteristics: drain current as a function of drain-source voltage; typical values.



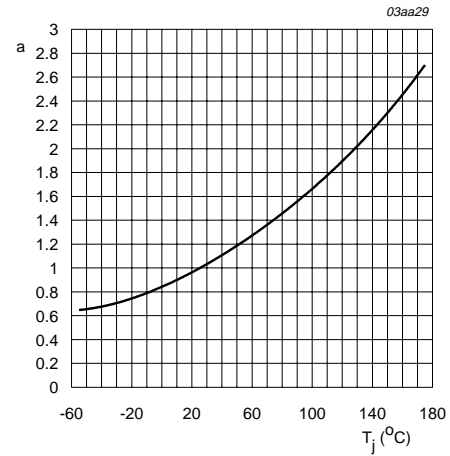
$T_j = 25\text{ }^\circ\text{C}$ and $175\text{ }^\circ\text{C}$; $V_{DS} > I_D \times R_{DSon}$

Fig 7. Transfer characteristics: drain current as a function of gate-source voltage; typical values.



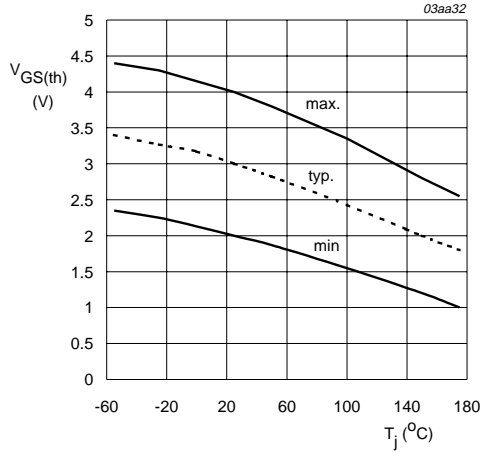
$T_j = 25\text{ }^\circ\text{C}$

Fig 8. Drain-source on-state resistance as a function of drain current; typical values.



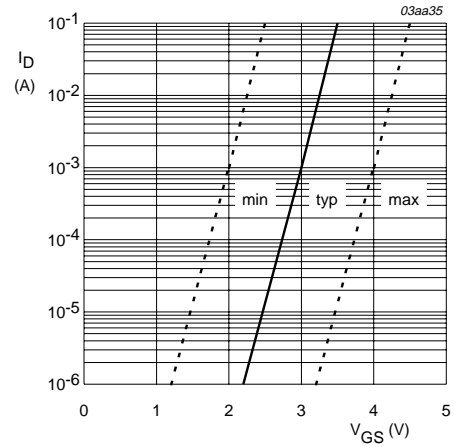
$$a = \frac{R_{DSon}}{R_{DSon(25^\circ\text{C})}}$$

Fig 9. Normalized drain-source on-state resistance factor as a function of junction temperature.



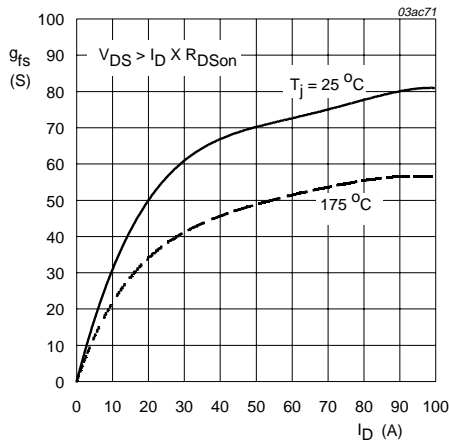
$I_D = 1 \text{ mA}; V_{DS} = V_{GS}$

Fig 10. Gate-source threshold voltage as a function of junction temperature.



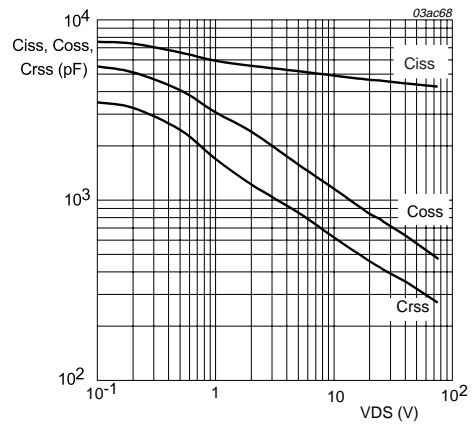
$T_j = 25 \text{ }^{\circ}C; V_{DS} = 5 \text{ V}$

Fig 11. Sub-threshold drain current as a function of gate-source voltage.



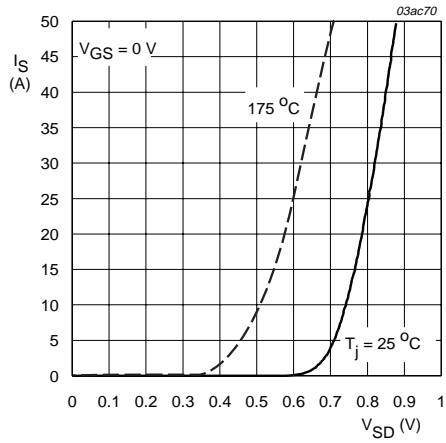
$T_j = 25 \text{ }^{\circ}C$ and $175 \text{ }^{\circ}C; V_{DS} > I_D \times R_{DSon}$

Fig 12. Forward transconductance as a function of drain current; typical values.



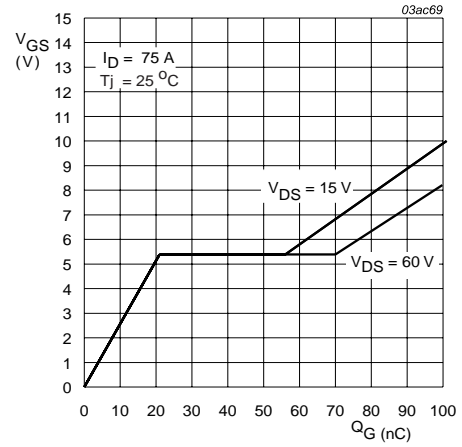
$V_{GS} = 0 \text{ V}; f = 1 \text{ MHz}$

Fig 13. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values.



$T_j = 25^\circ\text{C}$ and 175°C ; $V_{GS} = 0\text{ V}$

Fig 14. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values.



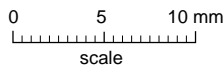
$I_D = 75\text{ A}$; $V_{DS} = 15\text{ V}$ and 60 V

Fig 15. Gate-source voltage as a function of gate charge; typical values.

9. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	b ₁	c	D	D ₁	E	e	L	L ₁	L ₂ ⁽¹⁾ max.	P	q	Q
mm	4.5	1.39	0.9	1.3	0.7	15.8	6.4	10.3	2.54	15.0	3.30	3.0	3.8	3.0	2.6
	4.1	1.27	0.7	1.0	0.4	15.2	5.9	9.7		13.5	2.79		3.6	2.7	2.2

Note

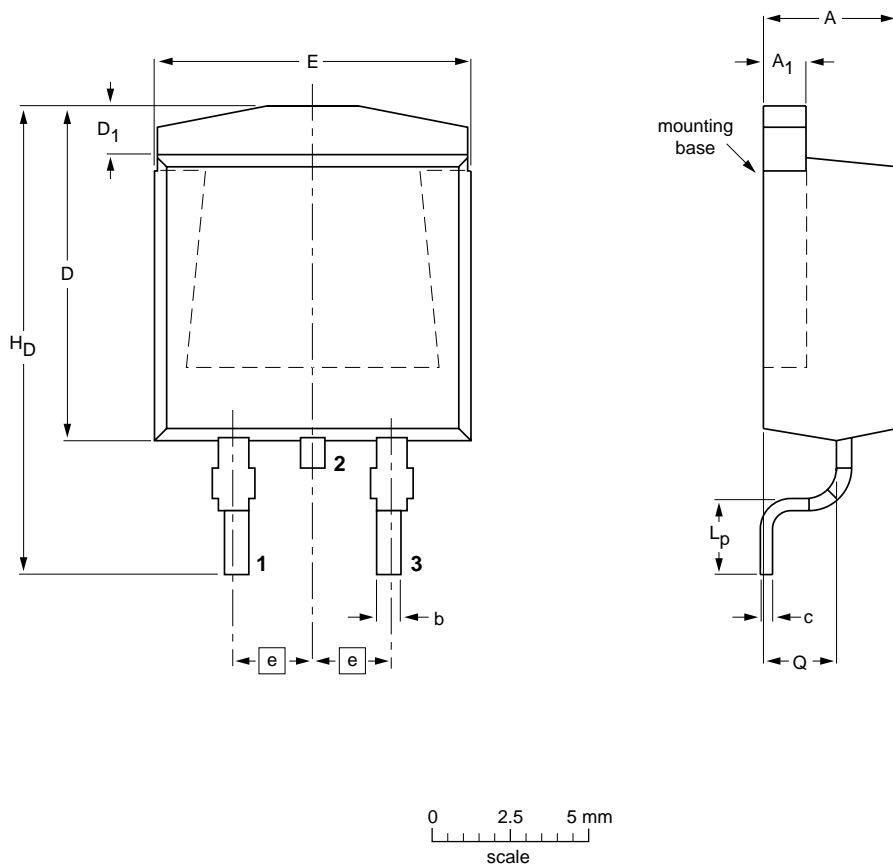
1. Terminals in this zone are not tinned.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT78		3-lead TO-220AB	SC-46			99-09-13 00-09-07

Fig 16. SOT78

Plastic single-ended surface mounted package (Philips version of D²-PAK); 3 leads
(one lead cropped)

SOT404



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁	b	c	D max.	D ₁	E	e	L _p	H _D	Q
mm	4.50 4.10	1.40 1.27	0.85 0.60	0.64 0.46	11	1.60 1.20	10.30 9.70	2.54	2.90 2.10	15.40 14.80	2.60 2.20

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ		
SOT404					98-12-14 99-06-25

Fig 17. SOT404 (D²-PAK).

10. Revision history

Table 6: Revision history

Rev	Date	CPCN	Description
01	20000918	-	Product specification.

11. Data sheet status

Datasheet status	Product status	Definition ^[1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product specification	Production	This data sheet contains final specifications. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.

[1] Please consult the most recently issued data sheet before initiating or completing a design.

12. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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